

MICRO BOARD STACKER

SPECIFICATIONS

For complete specifications see www.samtec.com?DWM or www.samtec.com?HDWM

Insulator Material:

LCP

Terminal Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +105 °C with Tin

-55 °C to +125 °C with Gold

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.15 mm) .006" max*

*(.004" stencil solution may be available; contact IPG@samtec.com)

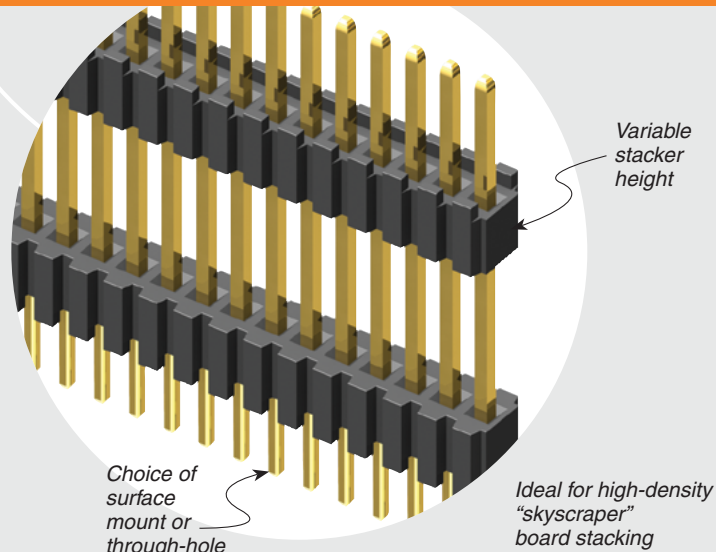
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

Mates with:
SMS, SLM, RSM



TYPE STRIP	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	ROW OPTION	STACKER HEIGHT	OTHER OPTION
	01 thru 50	Specify LEAD STYLE from chart	-L = 10 μ " (0.25 μ m) Gold contact, Matte Tin on tail -G = 10 μ " (0.25 μ m) Gold on post, Gold flash on tail	-S = Single Row -D = Double Row	"XXX" = Stacker Height Example: -250 = (6.35 mm) .250"	"XXX" = Polarized Position (Specify position of omitted pin) -SM = Surface Mount (Requires HDWM. 02 thru 40 positions only.) -A = Alignment Pin (Requires HDWM. 6 positions min -D only.) Metal or plastic at Samtec discretion (N/A with -LC) -LC = Locking Clip (Requires HDWM. (5 positions min. -D only) (N/A with -A) (Manual placement required) -P = Pick & Place Pad (Requires HDWM)

LEAD STYLE	OAL	
	THROUGH-HOLE	SURFACE MOUNT
-01	(11.43) .450	(8.38) .330
-51	(10.41) .410	—
-52	(10.80) .425	—
-53	(12.83) .505	(9.78) .385
-54	(14.10) .555	(11.05) .435
-55	(15.49) .610	(12.45) .490
-56	(15.88) .625	(12.83) .505
-57	(16.51) .650	(13.46) .530
-58	(17.91) .705	(14.86) .585
-59	(19.18) .755	(15.62) .615
-60	(20.96) .825	—
-61	(26.67) 1.050	—

Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.